

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YI-HUAN CHEN	12/07/2018
CHIEN-CHIH CHOU	12/07/2018
TA-WEI LIN	12/07/2018
HSIAO-CHIN TUAN	12/19/2018
ALEXANDER KALNITSKY	12/18/2018
KONG-BENG THEI	12/07/2018
CHIA-HONG WU	12/07/2018
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16169220
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ATTORNEY DOCKET NUMBER:	TSMCP938US
NAME OF SUBMITTER:	JAMES R. POTASHNIK
SIGNATURE:	/James R. Potashnik/

PATENT

DATE SIGNED:	12/26/2018
Total Attachments: 9 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif source=Assignment#page5.tif source=Assignment#page6.tif source=Assignment#page7.tif source=Assignment#page8.tif source=Assignment#page9.tif	

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):
Yi-Huan Chen

Assignor(s):
Chien-Chih Chou

Assignor(s):
Ta-Wei Lin

Assignor(s):
Hsiao-Chin Tuan

Assignor(s):
Alexander Kalnitsky

Assignor(s):
Kong-Beng Thei

Assignor(s):
Chia-Hong Wu

Assignee:
Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
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Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

"FUSI GATED DEVICE FORMATION" for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this
Assignment on the same day as he/she signs the Declaration); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. _____

filed on _____

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for

TSMC Docket No. P20181054US00

Docket No. TSMCP938US

United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2018.12.07
Date

Yi-Huan Chen
Name 1st Inventor Yi-Huan Chen

TSMC Docket No. P20181054US00
Docket No. TSMCP938US

2018-12-07
Date

Chien-Chih Chou
Name 2nd Inventor Chien-Chih Chou


TSMC Docket No. P20181054US00
Docket No. TSMCP938US

2018-12-07
Date

Ta Wei Lin
Name 3rd Inventor Ta-Wei Lin

TSMC Docket No. P20181054US00
Docket No. TSMCP938US

12/19/18
Date


Name 4th Inventor Hsiao-Chin Tuan

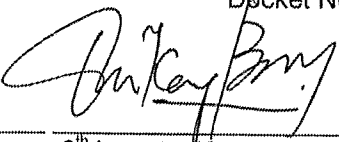
TSMC Docket No. P20181054US00
Docket No. TSMCP938US

12/18/2018
Date


Name 5th Inventor Alexander Kalnitsky

TSMC Docket No. P20181054US00
Docket No. TSMCP938US

12/17 '18
Date


Name 6th Inventor Kong-Beng Thei

TSMC Docket No. P20181054US00
Docket No. TSMCP938US

12/07/2018
Date

吳志宏 Chia-Hong Wu
Name 7th Inventor Chia-Hong Wu